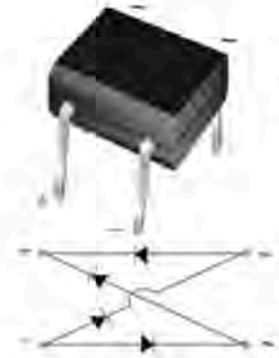


### Features

- ◆ Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- ◆ Glass passivated chip junctions
- ◆ Fast recovery, low switching loss
- ◆ High temperature soldering guaranteed: 260°C/10 seconds
- ◆ Long pointed leads: 3.70mm-4.05mm



Package: MBM

### Mechanical Data

- ◆ Case: Molded plastic body over passivated junctions
- ◆ Terminals: plated leads solderable per MIL-STD-750, Method 2026
- ◆ Polarity: Polarity symbols marked on body
- ◆ Mounting Position: Any
- ◆ Weight: 0.078 oz., 0.22g

### Maximum Ratings & Electrical Characteristics

(T<sub>A</sub>=25°C unless otherwise noted)

Parameter	Symbol	RMB2M	RMB4M	RMB6M	RMB8M	RMB10M	Unit
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	200	400	600	800	1000	V
Maximum RMS voltage	V <sub>RMS</sub>	140	280	420	560	700	V
Maximum DC blocking voltage	V <sub>DC</sub>	200	400	600	800	1000	V
Maximum Average forward output current (see Fig.1) on glass-epoxy P.C.B on aluminum substrate	I <sub>F(AV)</sub>			0.5 <sup>(1)</sup> 0.8 <sup>(2)</sup>			A
Peak forward surge current 8.3 MS single HALF sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>			30			A
Rating for fusig (t<8.3ms)	i <sup>2</sup> t			5			A <sup>2</sup> sec
Maximum instantaneous forward voltage drop per leg at 0.4A	V <sub>F</sub>			1.30			V
Maximum DC reverse current at T <sub>A</sub> =25°C rated DC blocking voltage per leg T <sub>A</sub> =125°C	I <sub>R</sub>			5 100			μA
Maximum reverse recovery time at I <sub>F</sub> =0.5A, I <sub>R</sub> =1.0A, I <sub>rr</sub> =0.25A	T <sub>rr</sub>	150		250	500		nS
Typical thermal resistance per leg	R <sub>θJA</sub> R <sub>θJA</sub> R <sub>θJL</sub>			85 <sup>(1)</sup> 70 <sup>(2)</sup> 20 <sup>(1)</sup>			°C/W
Typical junction capacitance per at 4.0V, 1.0MHz	C <sub>j</sub>			13			pF
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>STG</sub>			-55 to +150			°C

Notes: 1. On glass epoxy P.C.B. mounted on 0.05×0.05"(1.3×1.3mm) pads

2. On aluminum substrate P.C.B. with an area of 0.8×0.8" (20×20mm) mounted on 0.05×0.05"(1.3×1.3mm) solder pad

## Ratings and Characteristics Curves

( $T_A = 25^\circ\text{C}$  unless otherwise noted)

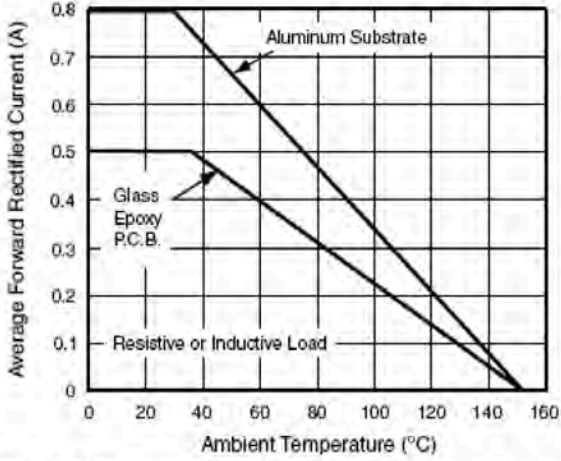


Figure 1. Derating Curve for Output Rectified Current

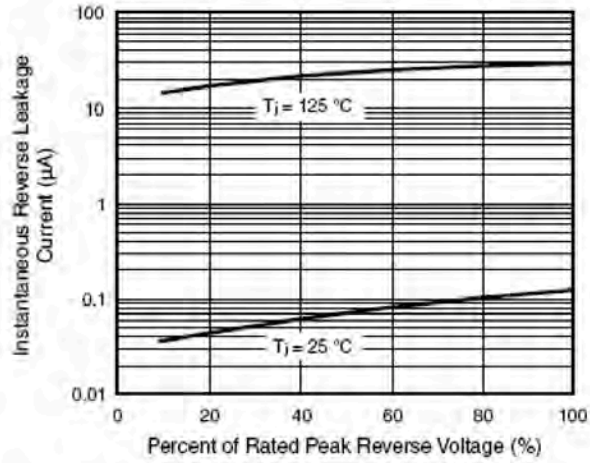


Figure 4. Typical Reverse Leakage Characteristics Per Leg

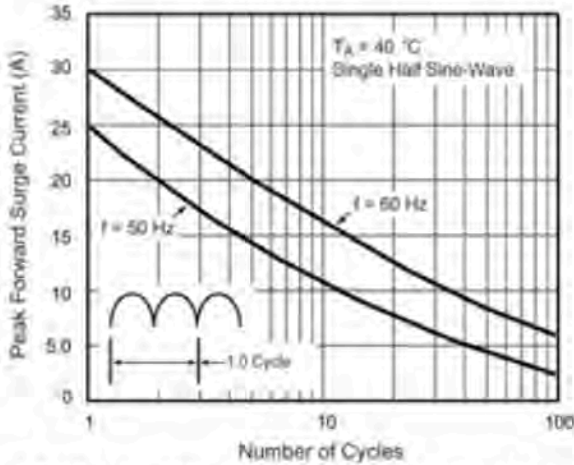


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current Per Leg

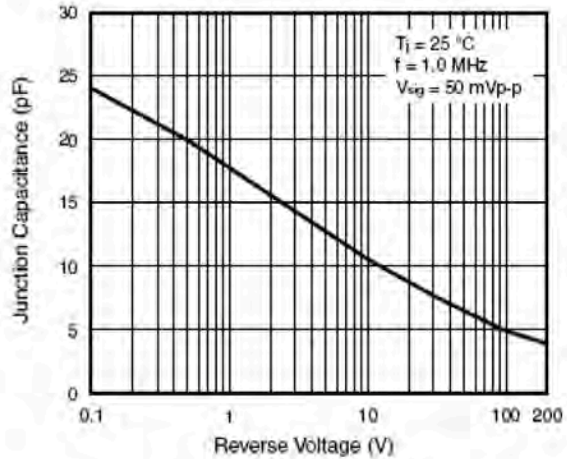


Figure 5. Typical Junction Capacitance Per Leg

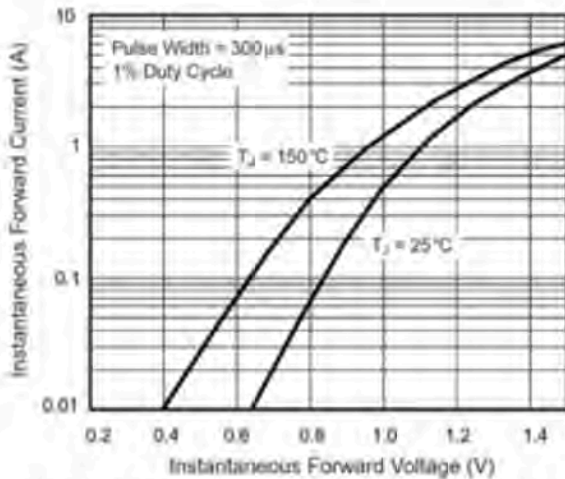
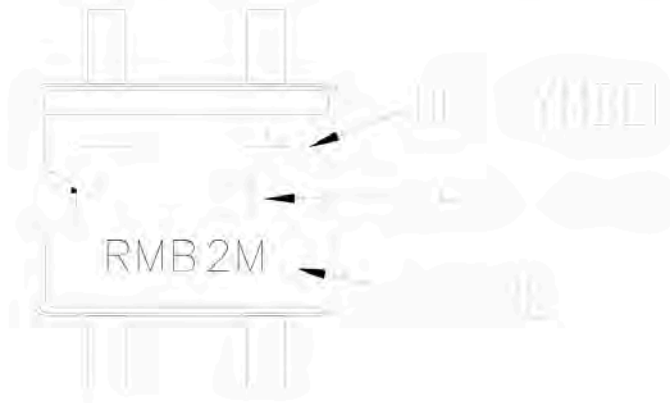


Figure 3. Typical Instantaneous Forward Characteristics Per Leg

## Marking



### DATE CODE

Year	2009	2010	2011	2012	2013	2014	2015	2016	2017	2018	2019	2020
Code	9	A	B	C	D	E	F	G	H	J	K	0
Month	1	2	3	4	5	6	7	8	9	10	11	12
Code	1	2	3	4	5	6	7	8	9	O	N	D

## Package Outline Dimensions

### Case Style MBM

